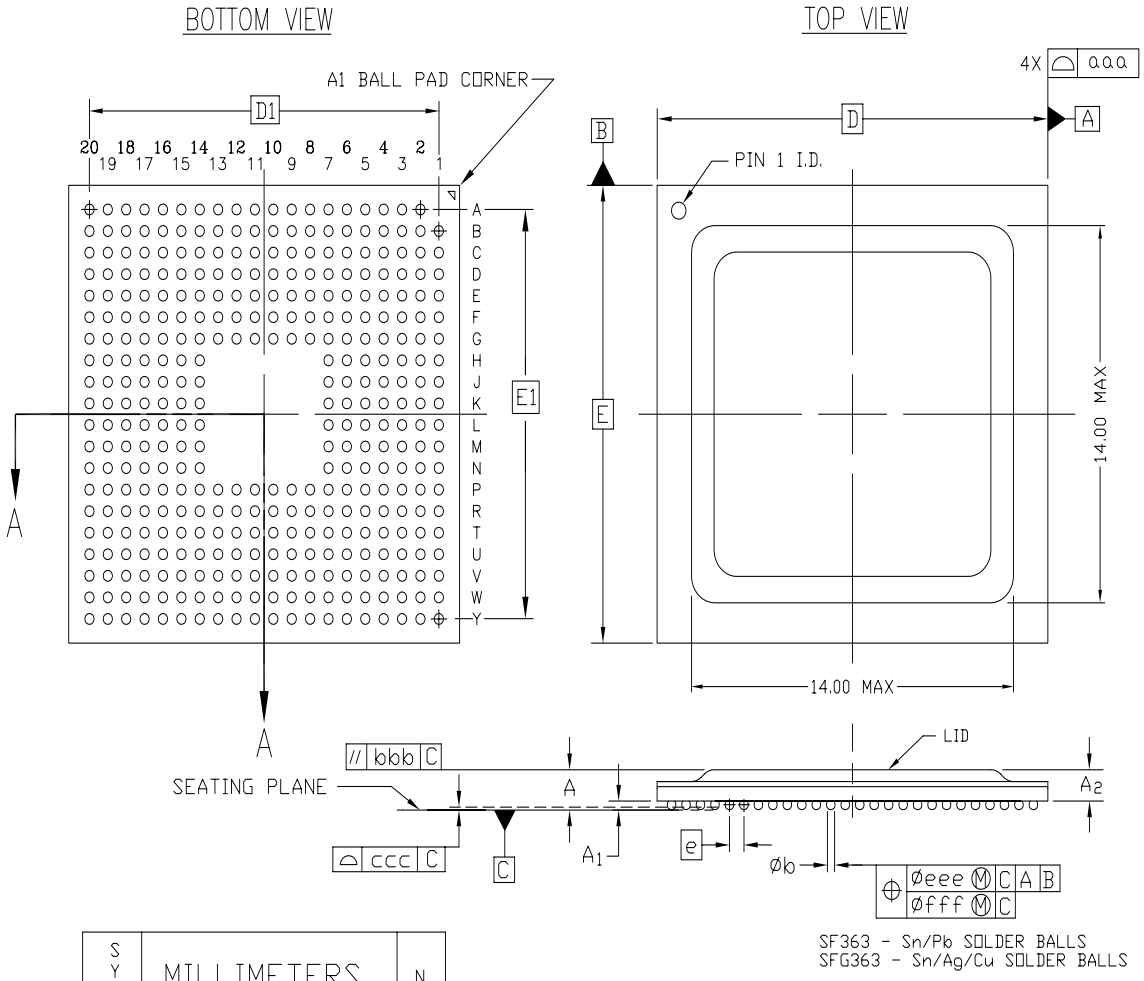
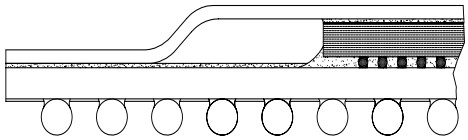
Flip-Chip BGA (SF363/SFG363) Package



SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A	—	1.79	1.99	3
A_1	0.36	0.40	0.44	
A_2	1.14	—	1.55	
D/E	17.00 BASIC			
D_1/E_1	15.20 REF			
e	0.80 BASIC			
øb	0.45	0.50	0.55	3
aaa	—	—	0.20	3
bbb	—	—	0.25	3
ccc	—	—	0.20	3
eee	—	—	0.25	3
fff	—	—	0.10	3
M	20			2



SECTION A–A
(NOT TO SCALE)

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M–1994
2. SYMBOL 'M' IS THE BALL MATRIX SIZE.
3. CONFORMS TO JEDEC MO–216–BAM–1 (DEPOPULATED) EXCEPT FOR DIMENSIONS "A", "øb" AND ASSOCIATED TOLERANCES AS NOTED.

363-BALL FLIP-CHIP BGA (SF363/SFG363)

© 2004-2008 Xilinx, Inc. All rights reserved. All Xilinx trademarks, registered trademarks, patents, and disclaimers are as listed at http://www.xilinx.com/legal.htm.
All other trademarks and registered trademarks are the property of their respective owners. All specifications are subject to change without notice.

www.BDTIC.com/XILINX

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
03/28/05	1.0.1	Minor editorial updates.
03/24/08	1.1	Updated JEDEC to MO-216-BAM-1. Added the SFG package prefix and material information.
6/10/08	1.2	Redefined “A2” dimension to point to top and bottom of package. Updated “A2” dimension table and changed JEDEC reference in the notes section.

www.BDTIC.com/XILINX